Binary/Decade Up/Down Counter

The MC14029B Binary/Decade up/down counter is constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. The counter consists of type D flip-flop stages with a gating structure to provide toggle flip-flop capability. The counter can be used in either Binary or BCD operation. This complementary MOS counter finds primary use in up/down and difference counting and frequency synthesizer applications where low power dissipation and/or high noise immunity is desired. It is also useful in A/D and D/A conversion and for magnitude and sign generation.

Features

- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Internally Synchronous for High Speed
- Logic Edge-Clocked Design Count Occurs on Positive Going Edge of Clock
- Asynchronous Preset Enable Operation
- Capable of Driving Two Low-Power TTL Loads or One Low-Power Schottky TTL Load Over the Rated Temperature Range
- Pin for Pin Replacement for CD4029B
- These Devices are Pb-Free and are RoHS Compliant
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable



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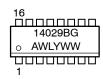
MARKING DIAGRAMS



PDIP-16 P SUFFIX CASE 648 ¹⁶**ስ** ሲ ሲ ሲ ሲ ሲ ሲ MC14029BCP o AWLYYWWG 1 ঢ় ତ ତ ତ ତ ତ ତ



SOIC-16 D SUFFIX CASE 751B



A = Assembly Location

WL = Wafer Lot
 YY, Y = Year
 WW = Work Week
 G = Pb-Free Indicator

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V _{in} , V _{out}	Input or Output Voltage Range (DC or Transient)	-0.5 to V _{DD} + 0.5	V
I _{in} , I _{out}	Input or Output Current (DC or Transient) per Pin	±10	mA
P _D	Power Dissipation, per Package (Note 1)	500	mW
T _A	Ambient Temperature Range	-55 to +125	°C
T _{stg}	Storage Temperature Range	-65 to +150	°C
T _L	Lead Temperature (8–Second Soldering)	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.

^{1.} Temperature Derating: Plastic "P and D/DW" Packages: - 7.0 mW/°C From 65°C To 125°C

TRUTH TABLE

Carry In	Up/Down	Preset Enable	Action
1	Х	0	No Count
0	1	0	Count Up
0	0	0	Count Down
X	Х	1	Preset

X = Don't Care

ORDERING INFORMATION

Device	Package	Shipping [†]		
MC14029BCPG	PDIP-16 (Pb-Free)	500 Units / Rail		
MC14029BDR2G	SOIC-16	2500 Units / Tape & Reel		
NLV14029BDR2G*	(Pb-Free)			

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

		V		− 55°C			25°C		125°C		
Characteristic		Symbol	V _{DD} Vdc	Min	Max	Min	Typ (Note 2)	Max	Min	Max	Unit
Output Voltage	"0" Level	V _{OL}	5.0		0.05	_	0	0.05	_	0.05	Vdc
$V_{in} = V_{DD}$ or 0			10	_	0.05	_	0	0.05	_	0.05	
			15	_	0.05	_	0	0.05	_	0.05	
	"1" Level	V _{OH}	5.0	4.95	_	4.95	5.0	_	4.95	_	Vdc
$V_{in} = 0$ or V_{DD}	1 20101		10	9.95	_	9.95	10	_	9.95	_	
VIII = 0 01 VDD			15	14.95	_	14.95	15	_	14.95	_	
Input Voltage	"0" Level	V _{IL}									Vdc
(V _O = 4.5 or 0.5 Vdc)			5.0		1.5	_	2.25	1.5	_	1.5	
(V _O = 9.0 or 1.0 Vdc)			10		3.0	_	4.50	3.0	_	3.0	
(V _O = 13.5 or 1.5 Vdc)			15	_	4.0	_	6.75	4.0	_	4.0	
	"1" Level	V _{IH}									Vdc
(V _O = 0.5 or 4.5 Vdc)	. 2010.		5.0	3.5	_	3.5	2.75	_	3.5	_	
(V _O = 1.0 or 9.0 Vdc)			10	7.0		7.0	5.50		7.0		
(V _O = 1.5 or 13.5 Vdc)			15	11		11	8.25	_	11		
Output Drive Current		I _{OH}									mAdc
(V _{OH} = 2.5 Vdc)	Source	011	5.0	- 3.0	_	- 2.4	- 4.2	_	- 1.7	_	
(V _{OH} = 4.6 Vdc)			5.0	- 0.64		- 0.51	- 0.88		- 0.36		
(V _{OH} = 9.5 Vdc)			10	- 1.6	_	- 1.3	- 2.25	_	- 0.9	_	
(V _{OH} = 13.5 Vdc)			15	- 4.2		- 3.4	- 8.8	_	- 2.4		
(V _{OL} = 0.4 Vdc)	Sink	l _{OL}	5.0	0.64	_	0.51	0.88	_	0.36	_	mAdc
(V _{OL} = 0.5 Vdc)			10	1.6		1.3	2.25	_	0.9		
(V _{OL} = 1.5 Vdc)			15	4.2	_	3.4	8.8		2.4	_	
Input Current		I _{in}	15	_	± 0.1	_	±0.00001	± 0.1	_	± 1.0	μAdc
Input Capacitance, (V _{in} = 0)		C _{in}			_	_	5.0	7.5	_	_	pF
Quiescent Current		I _{DD}	5.0	_	5.0	_	0.005	5.0	_	150	μAdc
(Per Package)			10	_	10	_	0.010	10	-	300	
			15	_	20	_	0.015	20	_	600	
Total Supply Current (Notes 3 & 4)		ΙΤ	5.0		•	I _T = (0	.58 μA/kHz)	f + I _{DD}	•	•	μAdc
(Dynamic plus Quiescent, Per Package)			10			$I_{T} = (1$.20 μA/kHz)	f + I _{DD}			
(C _L = 50 pF on all outputs, all buffers switching)			15			I _T = (1	.70 μA/kHz)	f + I _{DD}			

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

where: I_T is in μA (per package), C_L in pF, $V=(V_{DD}-V_{SS})$ in volts, f in kHz is input frequency, and k=0.001.

^{*}NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

^{4.} To calculate total supply current at loads other than 50 pF:

SWITCHING CHARACTERISTICS (1.) (C $_L$ = 50 pF, T_A = 25 $^{\circ}C)$

			All Types			
Characteristic	Symbol	V_{DD}	Min	Typ ^(2.)	Max	Unit
Output Rise and Fall Time $t_{TLH}, t_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$ $t_{TLH}, t_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$ $t_{TLH}, t_{THL} = (0.55 \text{ ns/pF}) C_L + 9.5 \text{ ns}$	t _{TLH} , t _{THL}	5.0 10 15	_ _ _	100 50 40	200 100 80	ns
Propagation Delay Time Clk to Q $t_{PLH},t_{PHL}=(1.7\;\text{ns/pF})\;C_L+230\;\text{ns}$ $t_{PLH},t_{PHL}=(0.66\;\text{ns/pF})\;C_L+97\;\text{ns}$ $t_{PLH},t_{PHL}=(0.5\;\text{ns/pF})\;C_L+75\;\text{ns}$	t _{PLH} , t _{PHL}	5.0 10 15	 	200 100 90	400 200 180	ns
Clk to $\overline{C_{\text{out}}}$ t_{PLH} , t_{PHL} = (1.7 ns/pF) C_{L} + 230 ns t_{PLH} , t_{PHL} = (0.66 ns/pF) C_{L} + 97 ns t_{PLH} , t_{PHL} = (0.5 ns/pF) C_{L} + 75 ns	t _{PLH} , t _{PHL}	5.0 10 15	_ _ _	250 130 85	500 260 190	ns
$\overline{C_{in}}$ to $\overline{C_{out}}$ t_{PLH} , t_{PHL} = (1.7 ns/pF) C_L + 95 ns t_{PLH} , t_{PHL} = (0.66 ns/pF) C_L + 47 ns t_{PLH} , t_{PHL} = (0.5 ns/pF) C_L + 35 ns	t _{PLH} , t _{PHL}	5.0 10 15	_ _ _	175 50 50	360 120 100	ns
PE to Q t_{PLH} , t_{PHL} = (1.7 ns/pF) C_L + 230 ns t_{PLH} , t_{PHL} = (0.66 ns/pF) C_L + 97 ns t_{PLH} , t_{PHL} = (0.5 ns/pF) C_L + 75 ns	t _{PLH} , t _{PHL}	5.0 10 15	_ _ _	235 100 80	470 200 160	ns
PE to $\overline{C_{out}}$ t_{PLH} , t_{PHL} = (1. 7 ns/pF) C_L + 465 ns t_{PLH} , t_{PHL} = (0.66 ns/pF) C_L + 192 ns t_{PLH} , t_{PHL} = (0.5 ns/pF) C_L + 125 ns	t _{PLH} , t _{PHL}	5.0 10 15	_ _ _	320 145 105	640 290 210	ns
Clock Pulse Width	t _{W(cl)}	5.0 10 15	180 80 60	90 40 30	_ _ _	ns
Clock Pulse Frequency	f _{cl}	5.0 10 15	_ _ _	4.0 8.0 10	2.0 4.0 5.0	MHz
Preset Removal Time The Preset Signal must be low prior to a positive-going transition of the clock.	t _{rem}	5.0 10 15	160 80 60	80 40 30	_ _ _	ns
Clock Rise and Fall Time	t _{r(cl)} t _{f(cl)}	5.0 10 1 5	_ _ _	_ _ _	15 5 4	μs
Carry In Setup Time	t _{su}	5.0 10 15	150 60 40	75 30 20	_ _ _	ns
Up/Down Setup Time		5.0 10 15	340 140 100	170 70 50	_ _ _	ns
Binary/Decade Setup Time		5.0 10 15	320 140 100	160 70 50	_ _ _	ns
Preset Enable Pulse Width	t₩	5.0 10 15	130 70 50	65 35 25	_ _ _	ns

The formulas given are for the typical characteristics only at 25°C.
 Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

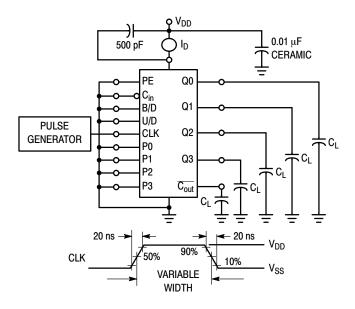


Figure 1. Power Dissipation Test Circuit and Waveform

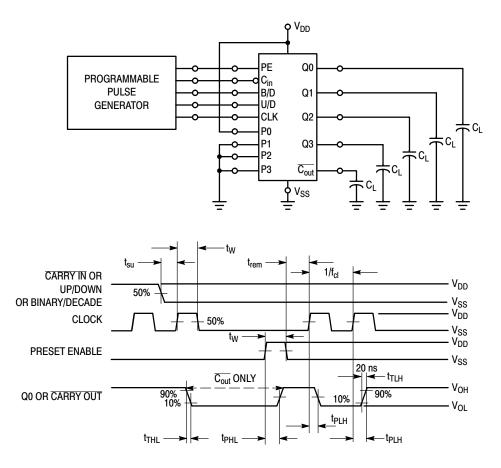
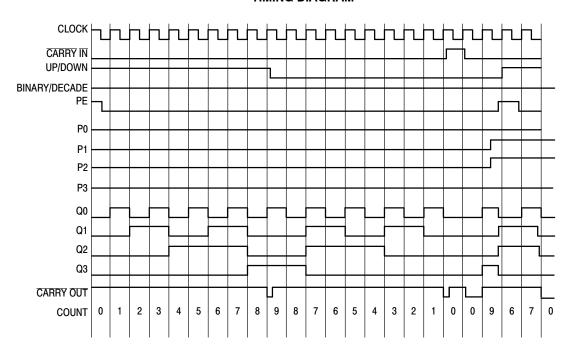
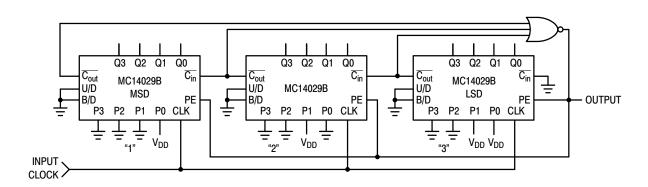


Figure 2. Switching Time Test Circuit and Waveforms

TIMING DIAGRAM





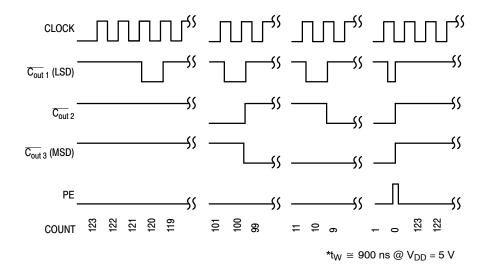
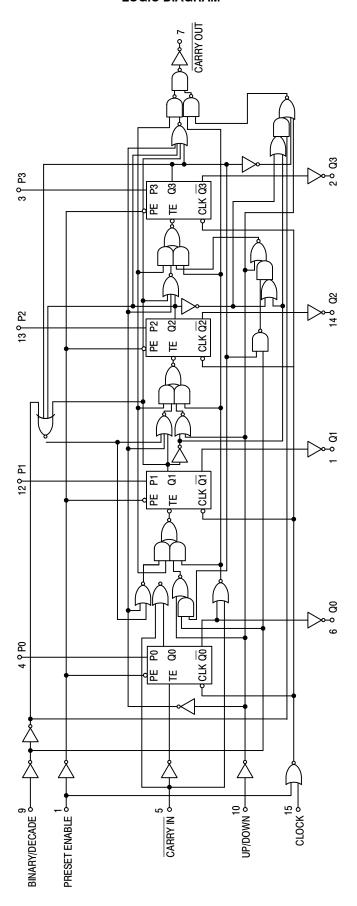
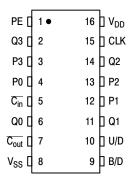


Figure 3. Divide by N BCD Down Counter and Timing Diagram (Shown for N = 123)

LOGIC DIAGRAM

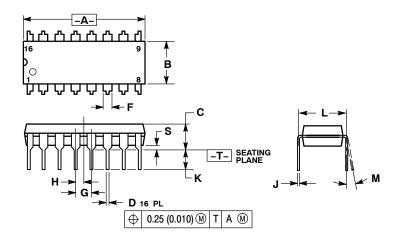


PIN ASSIGNMENT



PACKAGE DIMENSIONS

PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE CASE 648-08 **ISSUE T**



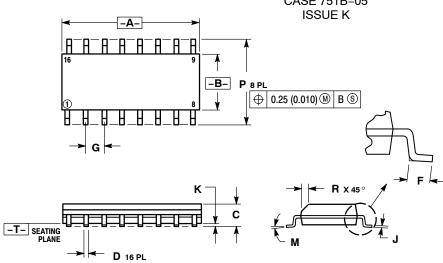
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS	
DIM	MIN MAX		MIN	MAX	
Α	0.740	0.740 0.770		19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.015 0.021		0.53	
F	0.040	0.70	1.02	1.77	
G	0.100 BSC		2.54 BSC		
Н	0.050 BSC		1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0 °	10 °	0°	10 °	
S	0.020	0.040	0.51	1.01	

PACKAGE DIMENSIONS

SOIC-16 D SUFFIX

PLASTIC SOIC PACKAGE CASE 751B-05



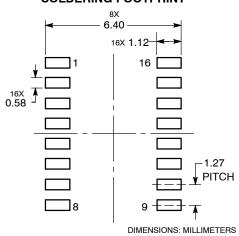
⊕ 0.25 (0.010) M T B S A S

NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
 Y14 5M 1982
- Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.
- 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 DIMENSION D DOES NOT INCLUDE DAMBAR
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES	
DIM	MIN MAX		MIN	MAX	
Α	9.80	10.00	0.386	0.393	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.25	0.016	0.049	
G	1.27	BSC	0.050 BSC		
J	0.19	0.25	0.008	0.009	
K	0.10	0.25	0.004	0.009	
M	0°	7°	0°	7°	
P	5.80	6.20	0.229	0.244	
R	0.25	0.50	0.010	0.019	

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